

# PATENT ABSTRACTS OF JAPAN

(11)Publication number : 2004-172323

(43)Date of publication of application : 17.06.2004

(51)Int.Cl.

H01L 25/065  
H01L 23/12  
H01L 25/07  
H01L 25/18

(21)Application number : 2002-335855

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(22)Date of filing : 20.11.2002

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## (54) SEMICONDUCTOR PACKAGE AND STACKED SEMICONDUCTOR PACKAGE

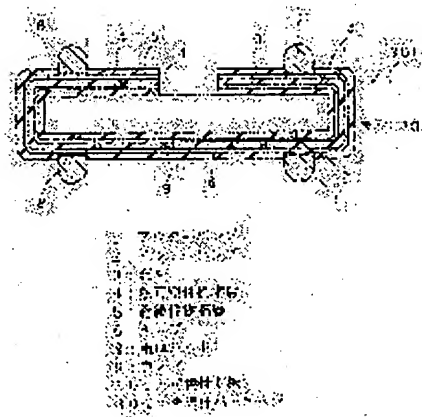
(57)Abstract:

PROBLEM TO BE SOLVED: To make the degree of flexibility of a design for external dimensions and re-interconnecting lines of a semiconductor package independent of a semiconductor device so as to provide a semiconductor package which can be easily packaged in a three-dimensional manner and to provide a three-dimensionally stacked semiconductor package.

SOLUTION: The semiconductor package is composed of a semiconductor device chip 6 and a flexible substrate 101 provided with a thermoplastic insulating resin layer 4. Electrodes provided on the flexible substrate 101 are connected to the prescribed electrodes of the

semiconductor device chip 6. The semiconductor device chip 6 is sealed up with the thermoplastic insulating resin

layer 4, the flexible substrate 101 is folded, and electrodes are formed on an electrode forming surface and the other surface. Interconnecting wirings 3 are provided in multilayer to the flexible substrate 101, a groove or a less layered part which differs from the other part in the number of wiring layers is provided to a folded part of the flexible board 101 or a region of the substrate 101 including a folded part, and a cavity is provided to a semiconductor device



mounting area. The flexible substrate 101 is folded at a prescribed position into a semiconductor package that is independent of the external dimensions of a semiconductor device.

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#### LEGAL STATUS

[Date of request for examination] 22.04.2005

[Date of sending the examiner's decision of rejection]

[Kind of final disposal of application other than the examiner's decision of rejection or application converted registration]

[Date of final disposal for application]

[Patent number]

[Date of registration]

[Number of appeal against examiner's decision of rejection]

[Date of requesting appeal against examiner's decision of rejection]

[Date of extinction of right]